${\bf (19) \ World \ Intellectual \ Property \ Organization}$

International Bureau





(43) International Publication Date 28 March 2002 (28.03.2002)

PCT

(10) International Publication Number WO 02/025702 A3

- (51) International Patent Classification⁷: H01L 23/495, 23/48, 23/52, 29/40
- (21) International Application Number: PCT/US01/27723
- (22) International Filing Date:

20 September 2001 (20.09.2001)

- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data: 09/665,898 20 September 2000 (20.09.2000) US
- (71) Applicants and
- (72) Inventors: KIM, Stephen, M. [US/KR]; 493-3 Sungsung-Dong, Cheonan-Si, Choongnam (KR). HONG, Soon, Sung [KR/KR]; 493-3 Sungsung-Dong, Cheonan-Si, Choongnam (KR). LEE, Ji, Yong [KR/KR]; 493-3 Sungsung-Dong, Cheonan-Si, Choongnam (KR). PARK, Byung, Jun [KR/KR]; 493-3 Sungsung-Dong, Cheonan-Si, Choongnam (KR). KWON, Hyok, Won [KR/KR]; 2nd Floor, Gunyang Building, 224-4 Poy-dong, Kangnam-ku, Seoul 135-964 (KR).

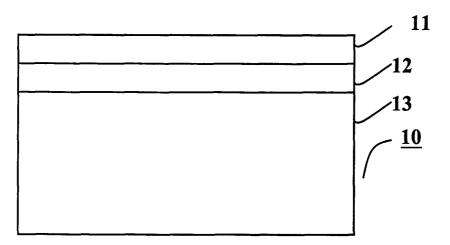
- (74) Agent: MOON, Soo, Lee; eFirm, Ltd., 6208A Old Franconia Road, Alexandria, VA 22310 (US).
- (81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.
- (84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- (88) Date of publication of the international search report: 1 August 2002

[Continued on next page]

(54) Title: SEMICONDUCTOR PRODUCT WITH A SILVER AND GOLD ALLOY



(57) Abstract: A semiconductor product (10) comprises a silver and gold alloy layer (11), wherein the silver and gold alloy forms an outside layer of the product (11). In some embodiments, a nickellayer (12) underlies the silver and gold alloy layer (11). In further embodiments, a copper layer (13) underlies the nickel layer (12). Moreover, the present invention pertains to a semiconductor substrate comprising a silver and gold alloy layer, wherein the silver and gold alloy forms an outside layer of the semiconductor substrate. The present invention has a particular application in having a silver and gold alloy form the outside layer of various items, including a lead frame, a board grid array, a header, a printed circuit board, a Reed switch, and a connector.





For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

International application No.
PCT/US01/27728

						
A. CLASSIFICATION OF SUBJECT MATTER IPC(7) :H01L 23/495, 23/48, 23/52, 29/40 US CL : 257/677, 787, 762, 779, 781; 174/257; 335/151; 439/524 According to International Patent Classification (IPC) or to both national classification and IPC						
B. FIELDS SEARCHED						
	cumentation searched (classification system followed	d by classification symbols)				
U.S. : 257/677, 737, 762, 779, 781; 174/257; 385/151; 489/524						
	on searched other than minimum documentation to	the extent that such documents are i	ncluded in the fields			
searchedals handbook desk edition and edition						
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used) Please See Extra Sheet.						
C. DOCUMENTS CONSIDERED TO BE RELEVANT						
Category*	Citation of document, with indication, where ap	propriate, of the relevant passages	Relevant to claim No.			
	US 6,081,310 A (Katsuya et al.) 27 Ju	ane 2000, col 10, line 49, to	1-30			
Y	col 11, line 13; col 12, lines 27-36.		136-165			
X Furthe	er documents are listed in the continuation of Box	C. See patent family annex.				
* Special categories of cited documents: "I" later document published after the international filing date or priority date and not in conflict with the application but cited to understand						
"A" document defining the general state of the art which is not considered the principle or theory underlying the invention to be of particular relevance "Y" document of particular relevance; the elaiwed invention cannot be						
"L" document which may throw doubts on priority claim(s) or which is when the document is taken alone						
speci	cited to establish the publication date of another citation or other special reason (as specified) "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined					
mean	means obvious to a person skilled in the art document published prior to the international filing date but later "&" document member of the same patent family					
_	the priority date claimed actual completion of the international search	Date of mailing of the international se	arch report			
Date of the actual completion of the international search 01 APRIL 2002 Date of mailing of the international search 2 3 APR 2007						
Commissioner of Patents and Trademarks		Authorized officer				
Box PCT Washington, D.C. 20231		FERIK KIELIN JHOOCHESO				
Fassimila NI-	(700) 007 0000	(T-11 N- Hoo) 000 7000				

International application No.
PCT/US01/27723

X JP Tal Y Y US	Citation of document, with indication, where appropriate, of the relevant	ant passages	Delement to 11 N
Y JP Fig			Relevant to claim No.
Y US	' 11-008341 A (Mori et al.) 12 January 1999 (12.01.9 ble 2	9), Fig. 1(c),	1, 3, 4, 7-11, 16, 18, 19, 22-26, 31, 33, 34, 37-41, 121, 123, 124, 127-131
	⁹ 05-117898 A (Morikawa et al.) 14 May 1993 (14.05.9 gs. 1-2, paragraphs, [0014], [0019], [0024]-[0026], [003		1, 3, 4, 7-11, 16, 18, 19, 22-26, 31, 33, 34, 37-41, 121, 123, 124, 127-131
	S 5,035,656 A (Patel) 30 July 1991 (30.07.91) Figures; -63; col 6, lines 15-32.	col 5, lines	1, 61-75, 106-120, 196-210, 241-255
Y US	S 3,342,568 A (Capillon) 19 September 1967 (19.09.67)), cols 1-2).	1, 61-75, 106-120, 196-210, 241-255
Y US	S 5,981,090 A (Ott) 9 November 1999 (09.11.99), cols.	1-2.	1, 61-75, 106-120, 196-210, 241-255
1	S 6,054,761 A (McCormack et al.) 25 April 2000 (25.0 a)-1(f); col 9, lines 4-37.	4.00), Figs	1-15, 46-60, 76-90, 181-195, 211-225
	S 3,668,355 A (Campbell et al.) 6 June 1972 (06.06.72) g. col 2, lines 52-73; claims 3, 6.), Abstract,	91-105, 226-240
	S 3,251,121 A (Prival) 17 May 1966 (17.05.66), Figs. 1 nes 5-34; col 4, lines 12-51.	1-2; col 3,	91, 93, 94, 97 92, 95, 96, 98-105, 226-240
1 _	IS 3,568,096 A (Kordos et al.) 2 March 1971 (02.03.71 l 1, line 69 to col 2, line 2; col 3, lines 37-57.	l) Abstract;	91, 93, 94 92, 95-105, 926-

International application No.
PCT/US01/27728

ategory*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No
χ -	US 3,634,048 A (Koons et al.) 11 January 1972 (11.01.72), Abstract, col 2, lines 54-61; col 3, lines 27-40, 52-57.	106-120, 241-255
7		1-105, 121-240, 256-270
7	US 3,600,794 A (Shibata et al.) 24 August 1971 (24.08.71), Abstract; col 4, lines 24-25.	1-270
	-	

Form PCT/ISA/210 (continuation of second sheet) (July 1998)*

International application No. PCT/US01/27728

B. FIELDS SEARCHED Electronic data bases consulted (Name of data base and where practicable terms used):				
EAST: ALL DATABASES; DIALOG search terms: gold, Au, silver, Ag, alloy, nickel, Ni, leadframe, header, ball (or bump) grid array, BGA, printed wiring (or circuit) board (or substrate), PWB, PCB, PWS, PCS, contact, bond, bonding, pad, connector, reed switch, percent, %, wt%, at%, mol%, ratio				
_				